



Material Content Data Sheet



Sales Product Name		IPD50R380CE		Issued		25. January 2018		
MA#		MA001811428						
Package		PG-TO252-3-343		Weight*		312.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.808	1.22	1.22	12177	12177
leadframe	inorganic material	phosphorus	7723-14-0	0.041	0.01		132	
	non noble metal	iron	7439-89-6	0.137	0.04		439	
	non noble metal	copper	7440-50-8	137.105	43.85	43.90	438399	438970
	non noble metal	aluminium	7429-90-5	0.453	0.14	0.14	1450	1450
wire	non noble metal	aluminium	7429-90-5	0.453	0.14	0.14	1450	1450
encapsulation	organic material	carbon black	1333-86-4	1.310	0.42		4190	
	plastics	epoxy resin	-	24.898	7.96		79612	
	inorganic material	silicondioxide	60676-86-0	104.833	33.52	41.90	335209	419011
leadfinish	non noble metal	tin	7440-31-5	3.834	1.23	1.23	12258	12258
solder	non noble metal	tin	7440-31-5	0.066	0.02		210	
	noble metal	silver	7440-22-4	0.082	0.03		262	
	non noble metal	lead	7439-92-1	3.134	1.00	1.05	10022	10494
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		32	
	non noble metal	iron	7439-89-6	0.033	0.01		106	
	non noble metal	copper	7440-50-8	32.995	10.55	10.56	105502	105640
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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